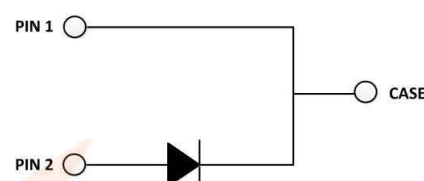


3rd Generation 1200V/5A SiC Schottky Barrier Diode

Features

- Revolutionary semiconductor material - Silicon Carbide (SiC)
- No reverse recovery
- High-speed switching performance
- Temperature-independent switching behavior
- System cost / size savings due to reduced cooling requirements
- Junction temperature range from -55°C to 175°C
- RoHS compliant



Potential Applications

- Industrial power supplies: Industrial UPS
- Battery chargers
- Solar inverters
- Switch mode power supplies

Package Type: TO-252-2L



Description

The HDS120J005L3 SiC Schottky Barrier Diode (SBD) has been developed using huashentai's advanced 3rd generation SiC SBD technology with the highest performance and reliability. It registers higher efficiency, higher operation temperature and lower loss and can be operated at higher frequency than Si-based solutions. As to the Schottky structure, it shows no recovery at turn-off and allows a low leakage current with reverse voltage up to 1200V. It can contribute to system miniaturization and achieve lightweight system design. Using RoHS compliant components, it is qualified for use in industrial application.

Product Specifications

Device	V_{RRM}	I_F (135°C)	V_F (25°C)	Q_c	Marking
HDS120J005L3	1200V	10A	1.35V	28nC	DS120005L3

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Table 1. Maximum Ratings

(T_c = 25°C, unless otherwise specified)

Parameter	Symbol	Value	Unit	Test conditions
Repetitive peak reverse voltage	V _{RRM}	1200	V	T _C = 25°C
Surge peak reverse voltage	V _{RSM}	1200		T _C = 25°C
DC reverse voltage	V _{DC}	1200		T _C = 25°C
Continuous forward current	I _F	22	A	T _C = 25°C
		10		T _C = 135°C
		5		T _C = 155°C
Surge non-repetitive forward current	I _{FSM}	55	A	T _C = 25°C, t _p = 10ms, half sine pulse
Surge repetitive forward current	I _{FRM}	40	A	T _C = 25°C, t _p = 10ms, half sine wave D = 0.1
Power dissipation	P _{tot}	134	W	T _C = 25°C
i ² t value	∫i ² dt	15	A ² s	T _C = 25°C, t _p = 10ms
Operating junction temperature	T _j	-55~175	°C	
Storage temperature	T _{stg}	-55~175	°C	

Table 2. Thermal Resistance

Parameter	Symbol	Values			Unit	Test condition
		Min.	Typ.	Max.		
Thermal resistance from junction to case	R _{th(j-c)}	/	1.12	/	°C/W	

Table 3. Static Electrical Characteristics

($T_j = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Values			Unit	Test conditions
		Min.	Typ.	Max.		
DC blocking voltage	V_{DC}	1200	/	/	V	$I_R = 100\ \mu\text{A}$
Forward voltage	V_F	/	1.35	1.50	V	$I_F = 5\text{A}$, $T_j = 25^\circ\text{C}$
		/	1.85	2.20		$I_F = 5\text{A}$, $T_j = 175^\circ\text{C}$
Reverse current	I_R	/	1	20	μA	$V_R = 1200\text{V}$, $T_j = 25^\circ\text{C}$
		/	3	80		$V_R = 1200\text{V}$, $T_j = 175^\circ\text{C}$

Table 4. Dynamic Electrical Characteristics

($T_j = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Values			Unit	Test conditions
		Min.	Typ.	Max.		
Total capacitance	C	/	400	/	pF	$V_R = 0\text{V}$, $f = 1\text{MHz}$
		/	27	/		$V_R = 400\text{V}$, $f = 1\text{MHz}$
		/	20	/		$V_R = 800\text{V}$, $f = 1\text{MHz}$
Total capacitive charge	Q_C	/	28	/	nC	$V_R = 800\text{V}$
Capacitance stored energy	E_C	/	8.2	/	μJ	$V_R = 800\text{V}$

Electrical Characteristic Diagrams

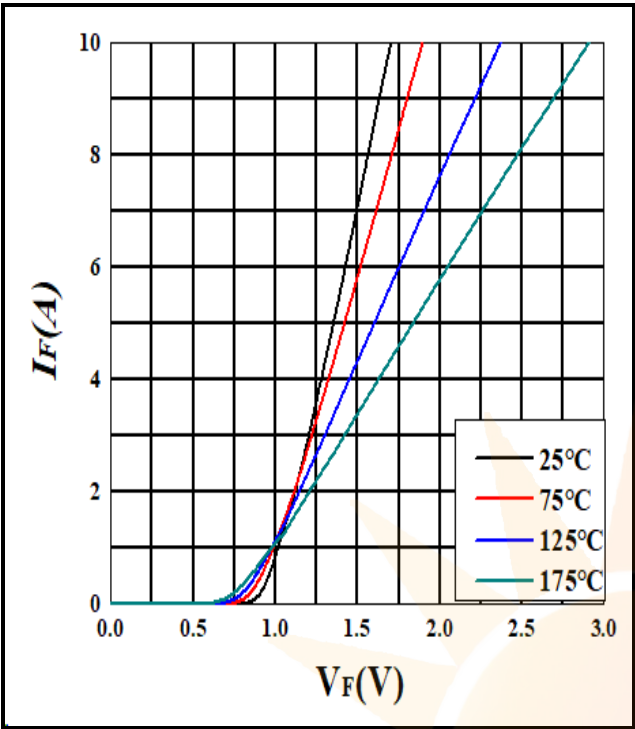


Figure 1. Forward characteristics

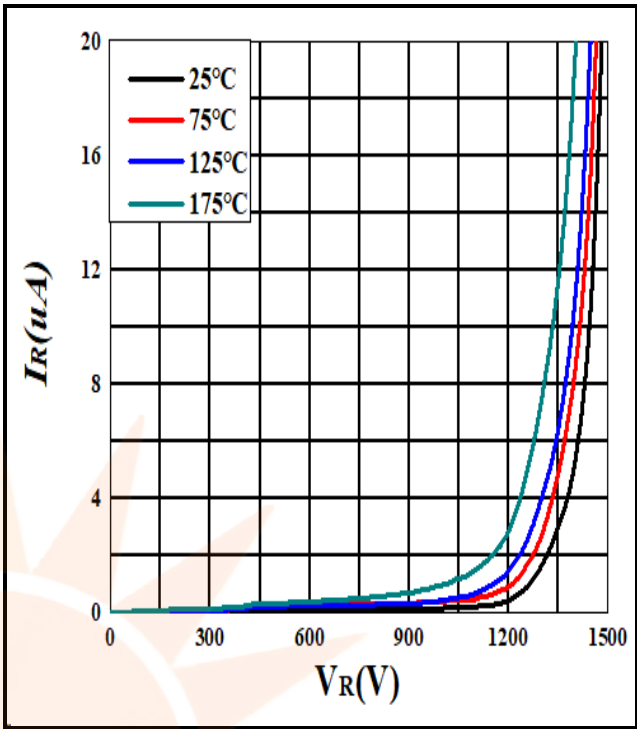


Figure 2. Reverse characteristics

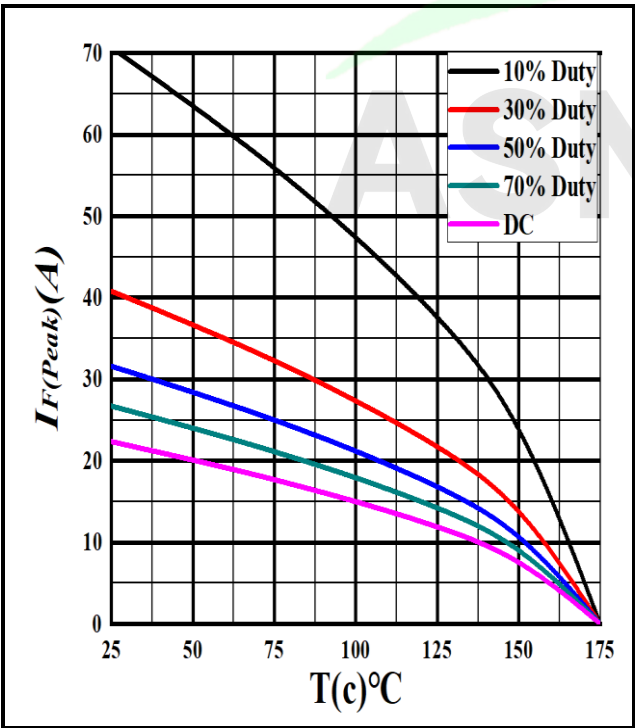


Figure 3. Current derating

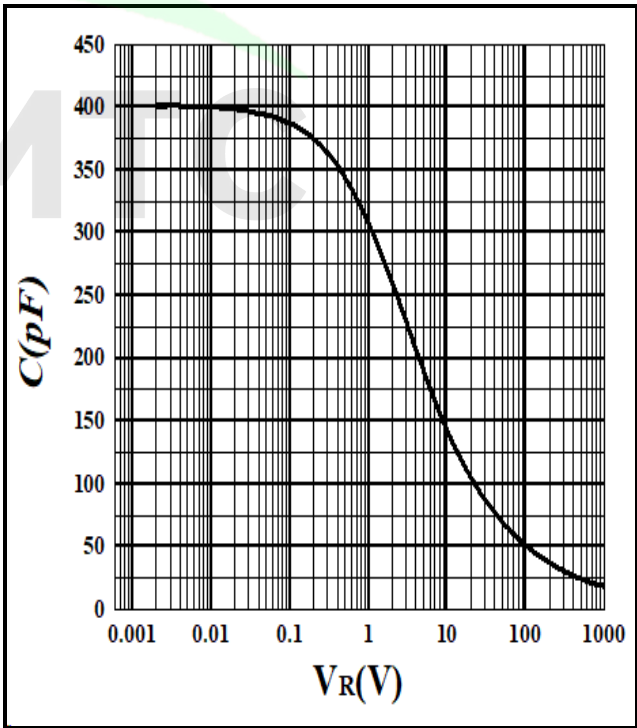


Figure 4. Capacitance vs. reverse voltage

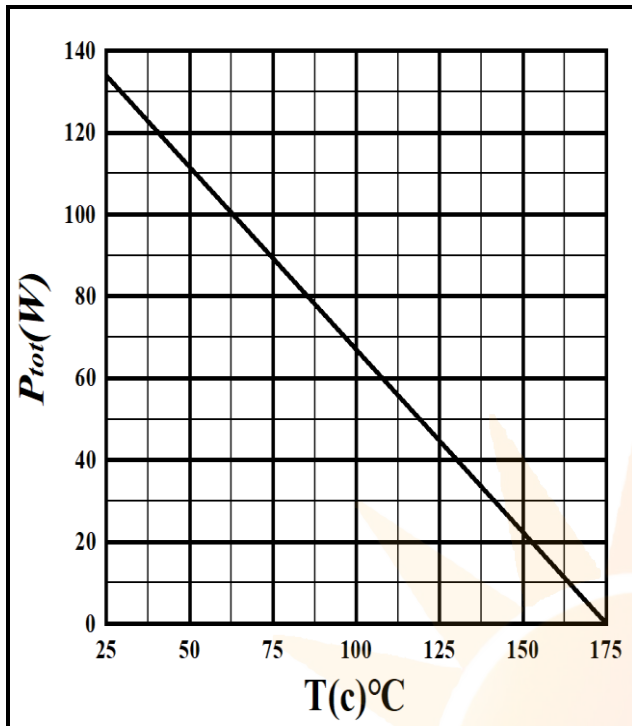


Figure 5. Power derating

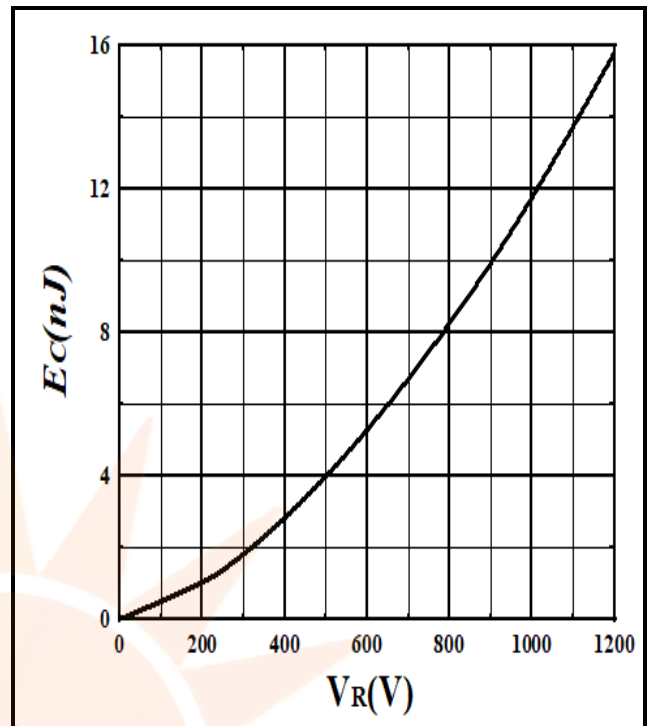


Figure 6. Capacitance stored energy

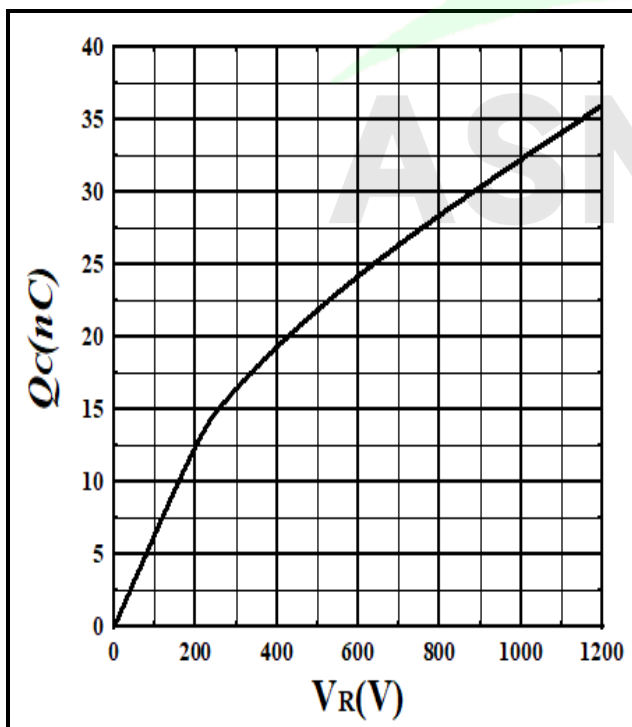
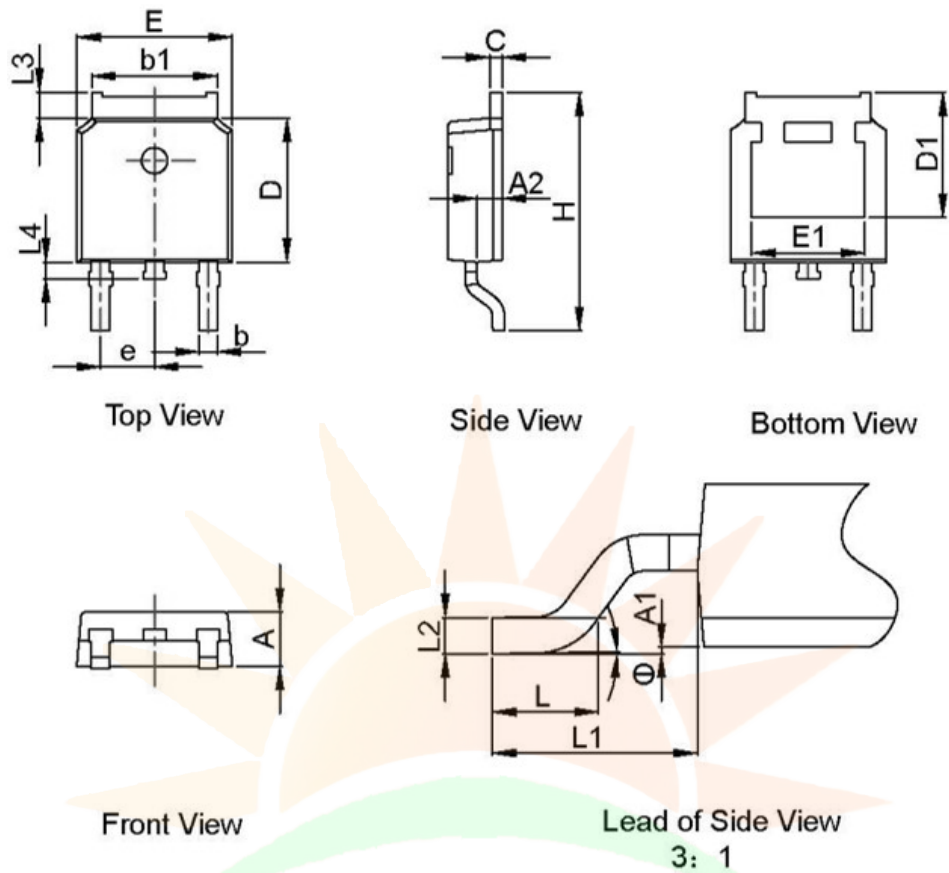


Figure 7. Total capacitance charge vs. reverse voltage

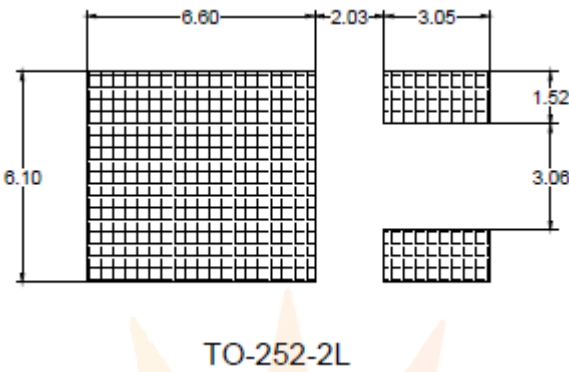
Package Information



Dimension unit: [mm]			
Symbol	Min	Nom	Max
A	2.20	2.30	2.38
A1	0	-	0.127
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b1	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	5.30 REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286 BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.743 REF		
L2	0.51 BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
θ	0°	-	8°

Recommended Solder Pad Layout

Note: All dimensions are in mm



Ordering Information

Part number	HDS120J005L3-ISARH
Package	TO-252-2L
Unit quantity	2500 EA
Packing type	Tape & Reel

Important Notices – Read Carefully

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